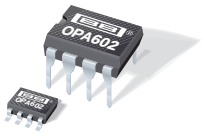


SBOS155A – AUGUST 1987 – REVISED OCTOBER 2002

High-Speed Precision *Difet*® OPERATIONAL AMPLIFIER

FEATURES

- **WIDE BANDWIDTH: 6.5MHz**
- **HIGH SLEW RATE: 35V/μs**
- **LOW OFFSET: ±250μV max**
- **LOW BIAS CURRENT: ±1pA max**
- **FAST SETTLING TIME: 1μs to 0.01%**
- **UNITY-GAIN STABLE**

APPLICATIONS

- **PRECISION INSTRUMENTATION**
- **OPTOELECTRONICS**
- **SONAR, ULTRASOUND**
- **PROFESSIONAL AUDIO EQUIPMENT**
- **MEDICAL EQUIPMENT**
- **DATA CONVERSION**

DESCRIPTION

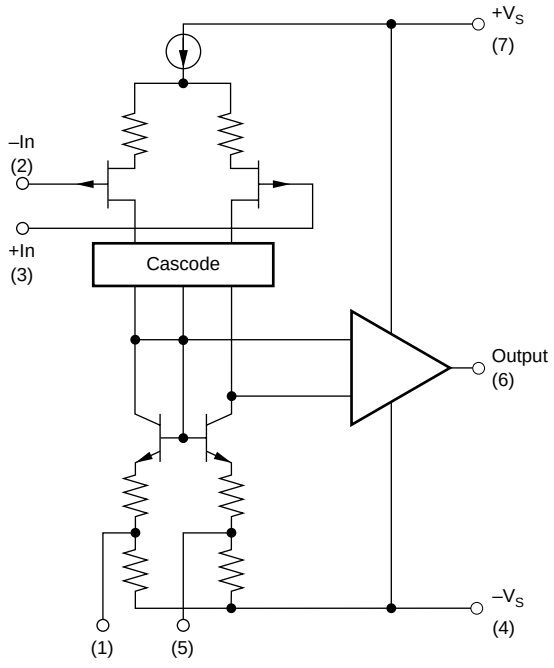
The OPA602 is a precision, wide bandwidth FET operational amplifier. Monolithic ***Difet*** (dielectrically isolated FET) construction provides an unusual combination of high-speed and accuracy.

Its wide-bandwidth design minimizes dynamic errors. High slew rate and fast settling time allow accurate signal processing in pulse and data conversion applications. Wide bandwidth and low distortion minimize AC errors. All specifications are rated with a 1kΩ resistor in parallel with 500pF load. The OPA602 is unity-gain stable and easily drives capacitive loads up to 1500pF.

Laser-trimmed input circuitry provides offset voltage and drift performance normally associated with precision bipolar op amps. ***Difet*** construction achieves extremely low input bias currents (1pA max) without compromising input voltage noise.

The OPA602's unique input cascode circuitry maintains low input bias current and precise input characteristics over its full input common-mode voltage range.

Difet® Burr-Brown Corp.



ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage	$\pm 18 V_{DC}$
Internal Power Dissipation ($T_J \leq +175°C$)	1000mW
Differential Input Voltage	Total V_S
Input Voltage Range	$\pm V_S$
Storage Temperature Range	
P and U Packages	–40°C to +125°C
Operating Temperature Range	
P and U Packages	–25°C to + 85°C
Lead Temperature	
U Package, SO (3s)	+260°C
Output Short-Circuit to Ground (+25°C)	Continuous
Junction Temperature	+175°C

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

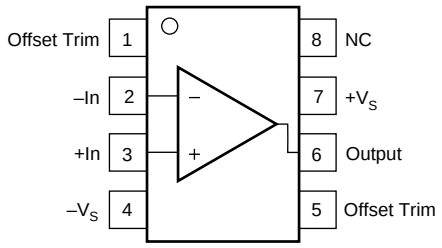
PACKAGE/ORDERING INFORMATION

PRODUCT	OFFSET VOLTAGE MAX (μV) AT 25°C	PACKAGE-LEAD	PACKAGE DESIGNATOR(1)	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
OPA602AP	±2000	DIP-8	P	–25°C to +85°C	602AP	602AP	Tubes, 50
OPA602BP	±1000	"	"	"	602BP	602BP	Tubes, 50
OPA602AU	±3000	SO-8	D	–25°C to +85°C	602AU	602AU	Tubes, 100

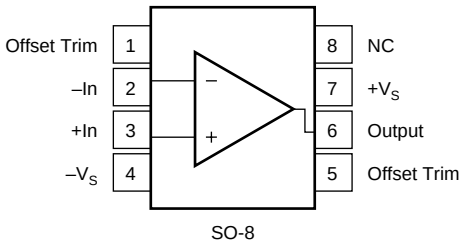
NOTE: (1) For the most current specifications and package information, refer to our web site at www.ti.com.

PIN CONFIGURATIONS

Top View **DIP, SO**



DIP-8



SO-8

NC = No Connection

ELECTRICAL CHARACTERISTICS

At $V_S = \pm 15V_{DC}$ and $T_A = +25°C$, unless otherwise noted.

PARAMETER	CONDITIONS	OPA602BP			OPA602AP, AU			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
INPUT NOISE								
Voltage:								
f_O = 10Hz			23			*		nV/√Hz
f_O = 100Hz			19			*		nV/√Hz
f_O = 1kHz			13			*		nV/√Hz
f_O = 10kHz			12			*		nV/√Hz
f_B = 10Hz to 10kHz			1.4			*		µVrms
f_B = 0.1Hz to 10Hz			0.95			*		µVp-p
Current:								
f_B = 0.1Hz to 10Hz			12			*		fAp-p
f_O = 0.1Hz to 20kHz			0.6			*		fA/√Hz
OFFSET VOLTAGE								
Input Offset Voltage:								
P Package			0.5	1		1	2	mV
U Package						1	3	mV
Over Specified Temperature								
P, U Packages			±0.75	±1.5		±1.5		mV
Average Drift[1]	$T_A = T_{MIN}$ to T_{MAX}		±3	±5		*	±15	µV/°C
Supply Rejection	$\pm V_S$ = 12V to 18V	80	100		70	*		dB
BIAS CURRENT								
Input Bias Current	$V_{CM} = 0V_{DC}$		±1	±2		±2	±10	pA
Over Specified Temperature			±20	±200		±20	±500	pA
OFFSET CURRENT								
Input Offset Current	$V_{CM} = 0V_{DC}$		0.5	2		1	10	pA
Over Specified Temperature			20	200		20	500	pA
INPUT IMPEDANCE								
Differential			10^{13} || 1			*		Ω || pF
Common-Mode			10^{14} || 3			*		Ω || pF
INPUT VOLTAGE RANGE								
Common-Mode Input Range		±10.2	+13, –11		*	*		V
Common-Mode Rejection	$V_{IN} = \pm 10V_{DC}$	88	100		75	*		dB
OPEN-LOOP GAIN, DC								
Open-Loop Voltage Gain	$R_L \geq 1k\Omega$	88	100		75	*		dB
FREQUENCY RESPONSE								
Gain Bandwidth	Gain = 100	4	6.5		3.5	*		MHz
Full-Power Response	20Vp-p, $R_L = 1k\Omega$		570			*		kHz
Slew Rate	$V_O = \pm 10V$, $R_L = 1k\Omega$	24	35		20	*		V/µs
Settling Time:								
0.1%	Gain = –1, $R_L = 1k\Omega$		0.6			*		µs
0.01%	C_L = 500pF, 10V Step		1.0					µs
RATED OUTPUT								
Voltage Output	$R_L = 1k\Omega$	±11.5	+12.9, –13.8		±11	*		V
Current Output	$V_O = \pm 10V_{DC}$	±15	±20		*	*		mA
Output Resistance	1MHz, Open Loop		80			*		Ω
Load Capacitance Stability	Gain = +1		1500			*		pF
Short-Circuit Current		±30	±50		±25	*		mA
POWER SUPPLY								
Rated Voltage			±15			*		V_{DC}
Voltage Range, Derated Performance		±5		±18	*		*	V_{DC}
Current, Quiescent	I_O = 0mADC		3	4		*	*	mA
Over Specified Temperature			3.5	4.5		*	*	mA
TEMPERATURE RANGE								
Specification	Ambient Temperature	–25		+85	*		*	°C
Operating:								
P, U Packages		–25		+85	*		*	°C
Storage:								
P, U Packages		–40		+125	*		*	°C
θ_{JA}		200			*		°C/W	

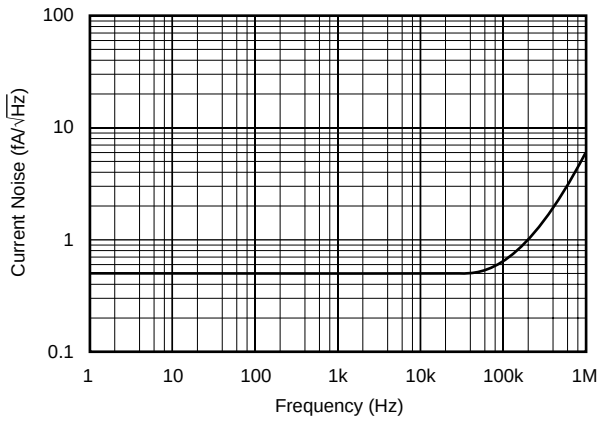
* Same specifications as OPA602BP.

NOTE: (1) OPA602AP, AU ensured by design with a 99% confidence level.

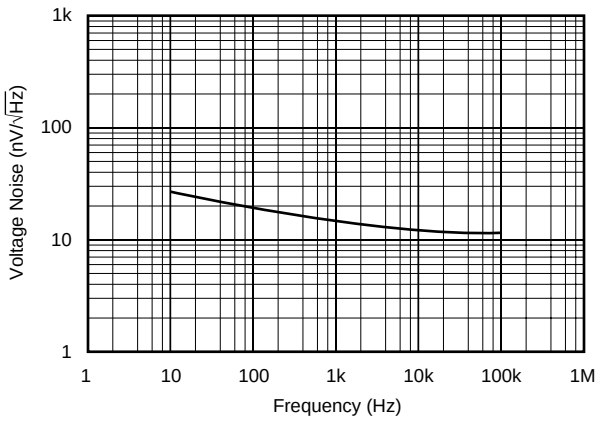
TYPICAL CHARACTERISTICS

At T_A = +25°C and V_S = ±15V_{DC}, unless otherwise noted.

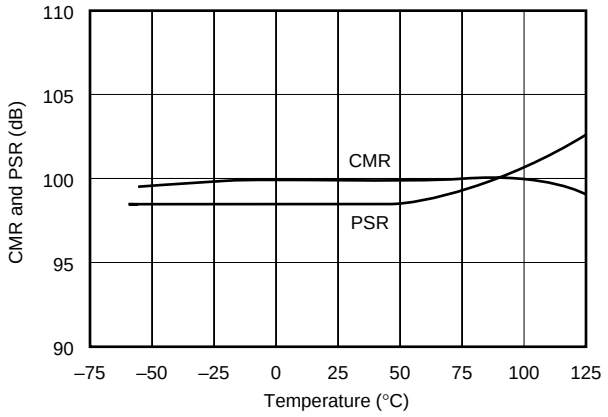
INPUT CURRENT NOISE SPECTRAL DENSITY



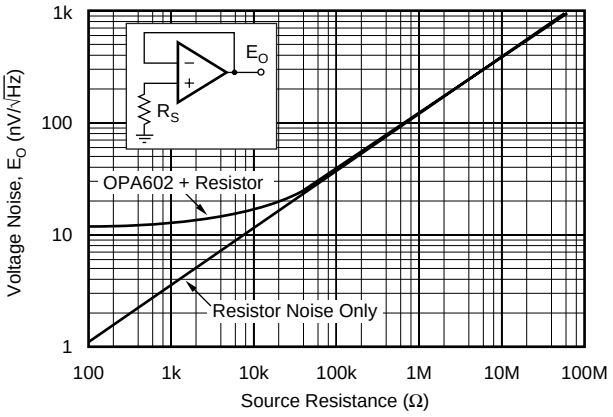
INPUT VOLTAGE NOISE SPECTRAL DENSITY



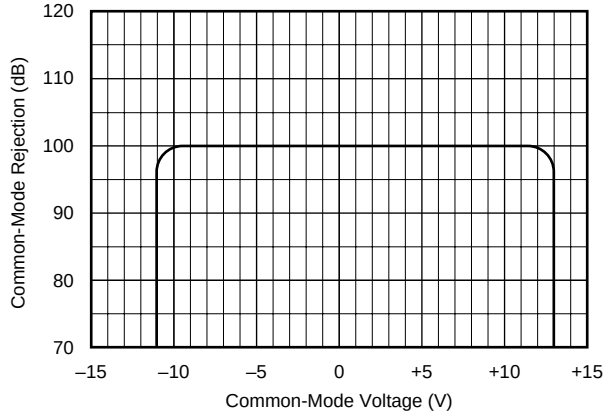
POWER-SUPPLY REJECTION AND COMMON-MODE REJECTION vs TEMPERATURE



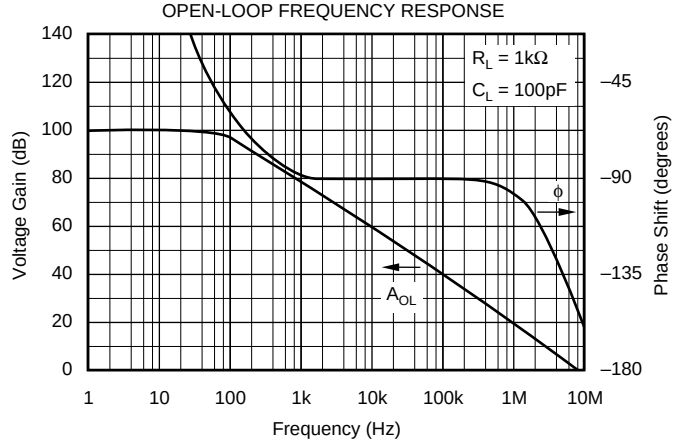
TOTAL INPUT VOLTAGE NOISE SPECTRAL DENSITY AT 1kHz vs SOURCE RESISTANCE



COMMON-MODE REJECTION vs INPUT COMMON-MODE VOLTAGE



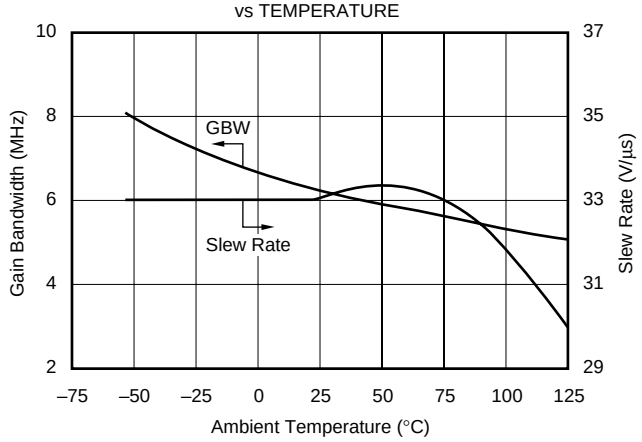
OPEN-LOOP FREQUENCY RESPONSE



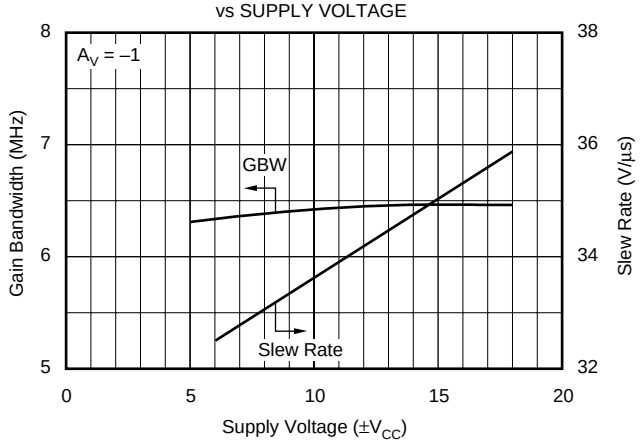
TYPICAL CHARACTERISTICS (Cont.)

At T_A = +25°C and V_S = ±15V_{DC}, unless otherwise noted.

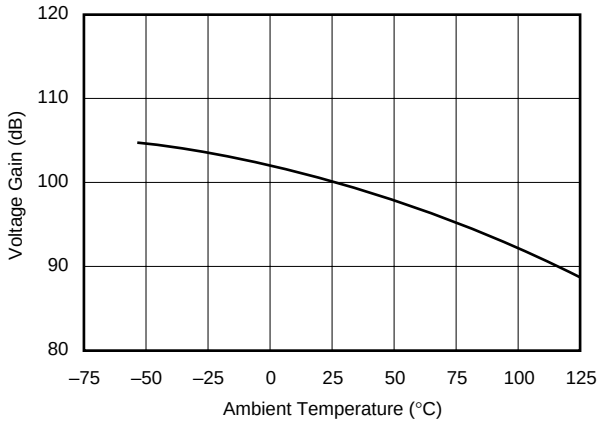
GAIN BANDWIDTH AND SLEW RATE vs TEMPERATURE



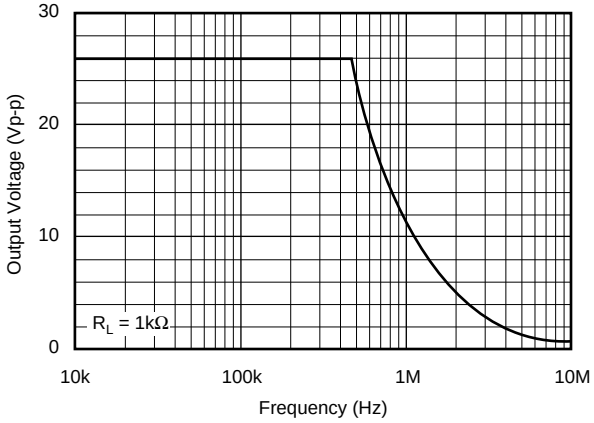
GAIN BANDWIDTH AND SLEW RATE vs SUPPLY VOLTAGE



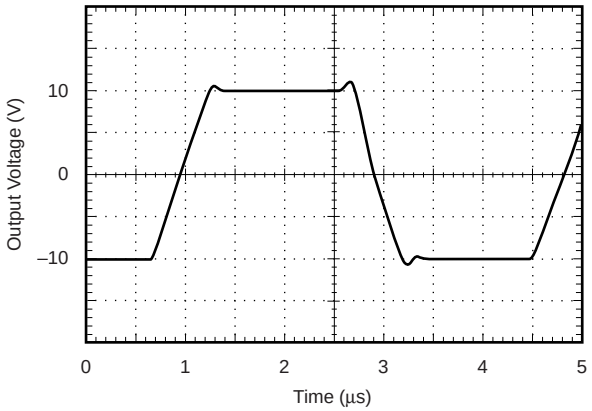
OPEN-LOOP GAIN vs TEMPERATURE



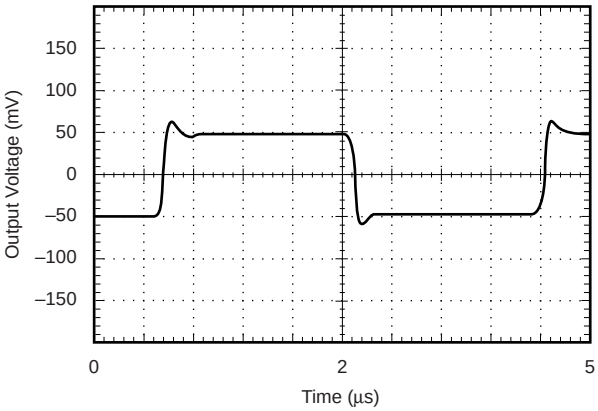
MAXIMUM OUTPUT VOLTAGE SWING vs FREQUENCY



LARGE-SIGNAL TRANSIENT RESPONSE



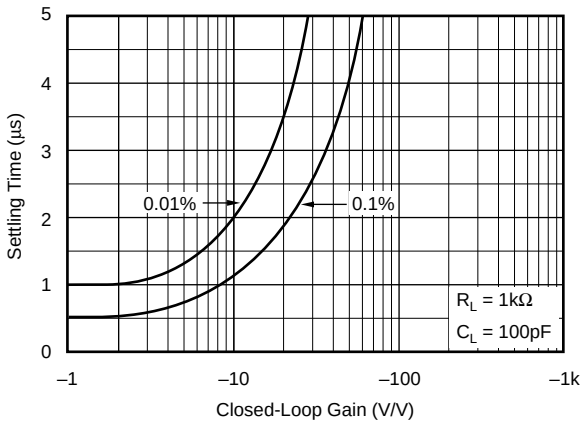
SMALL-SIGNAL TRANSIENT RESPONSE



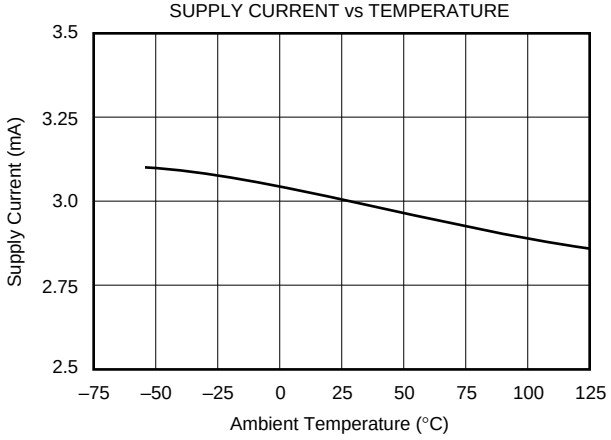
TYPICAL CHARACTERISTICS (Cont.)

At T_A = +25°C and V_S = ±15V_{DC}, unless otherwise noted.

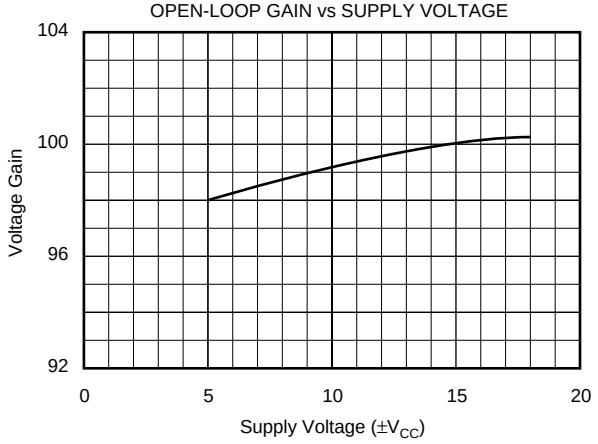
SETTLING TIME vs CLOSED-LOOP GAIN



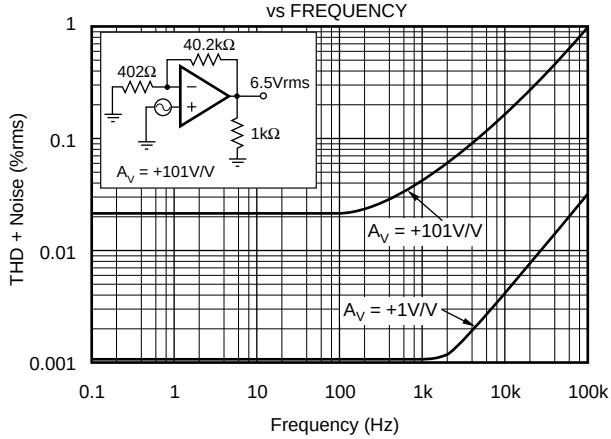
SUPPLY CURRENT vs TEMPERATURE



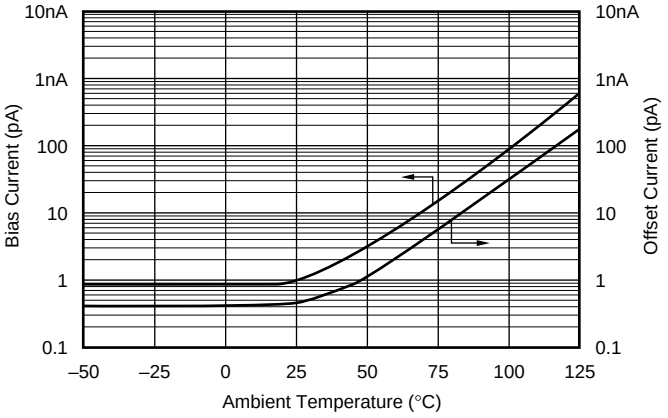
OPEN-LOOP GAIN vs SUPPLY VOLTAGE



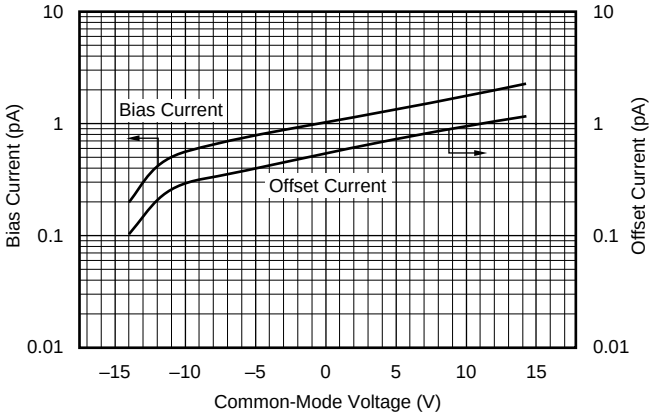
TOTAL HARMONIC DISTORTION vs FREQUENCY



BIAS AND OFFSET CURRENT vs TEMPERATURE

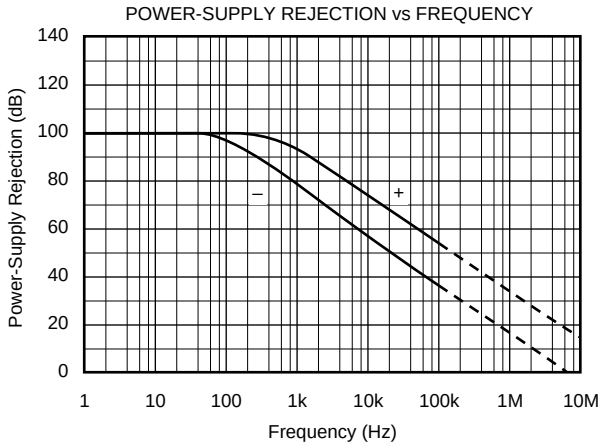


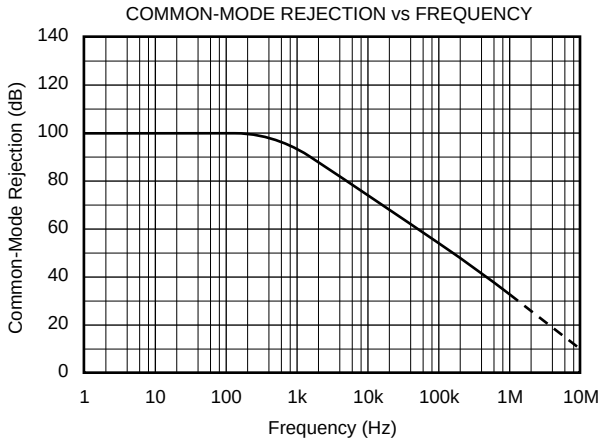
BIAS AND OFFSET CURRENT vs INPUT COMMON MODE VOLTAGE



TYPICAL CHARACTERISTICS (Cont.)

At T_A = +25°C and V_S = ±15V_{DC}, unless otherwise noted.





APPLICATIONS INFORMATION

Unity-gain stability with good phase margin and excellent output drive characteristics bring freedom from the subtle problems associated with other high-speed amplifiers. However, as with any high-speed, wide bandwidth circuitry, careful circuit layout will ensure best performance. Make short, direct interconnections and avoid stray wiring capacitance—especially at the inverting input pin.

Power supplies should be bypassed with good high-frequency capacitors positioned close to the op amp pins. In most cases 0.1µF ceramic capacitors are adequate. Applications with heavier loads and fast transient waveforms may benefit from use of additional 1.0µF tantalum bypass capacitors.

INPUT BIAS CURRENT GUARDING

Leakage currents across printed circuit boards can easily exceed the input bias current of the OPA602. A circuit board "guard" pattern, as shown in Figure 1, is an effective solution to difficult leakage problems. This guard pattern must be repeated on all layers of a multilayer board. By surrounding critical high impedance input circuitry with a low impedance circuit connection at the same potential, leakage currents will flow harmlessly to the low-impedance node.

Input bias current may also be degraded by improper handling or cleaning. Contamination from handling parts and circuit boards may be cleaned with appropriate solvents and deionized water. Each rinsing operation should be followed by a 30-minute bake at +85°C.

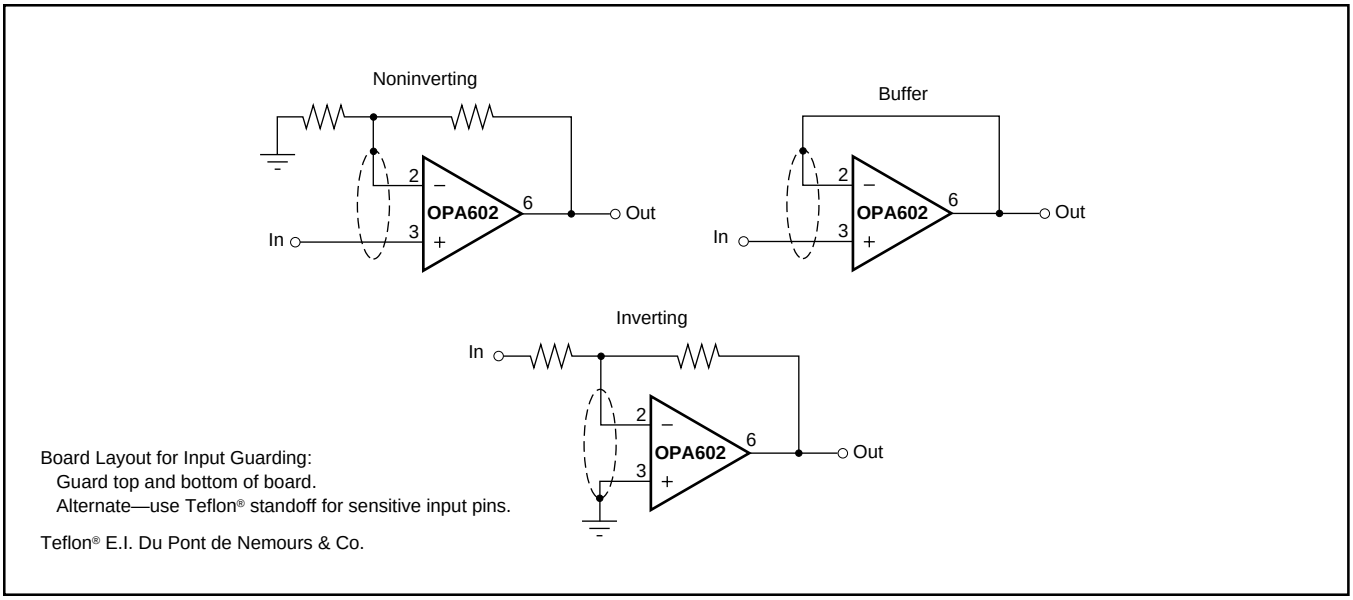
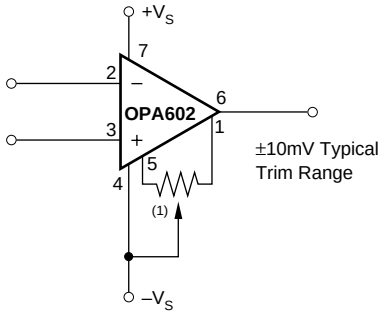


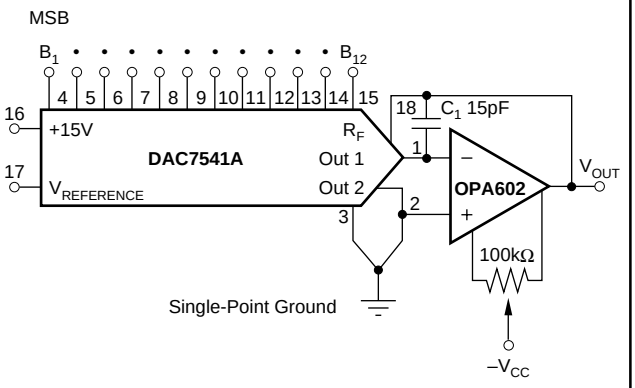
FIGURE 1. Connection of Input Guard.

APPLICATION CIRCUITS



NOTE: (1) 10kΩ to 1MΩ trim potentiometer (100kΩ recommended).

FIGURE 2. Offset Voltage Trim.



$$V_{OUT} = -V_{REF}\left(\frac{B_1}{2} + \frac{B_2}{4} + \frac{B_3}{8} + \cdots + \frac{B_{12}}{4096}\right)$$

$$-10V \le V_{REF} \le +10V$$

$$0 \le V_{OUT} \le -\frac{4095}{4096} V_{REF}$$

Where: B_N = 1 if the B_N digital input is high.
B_N = 0 if the B_N digital input is low.

FIGURE 3. Voltage Output Digital-to-Analog Converter.

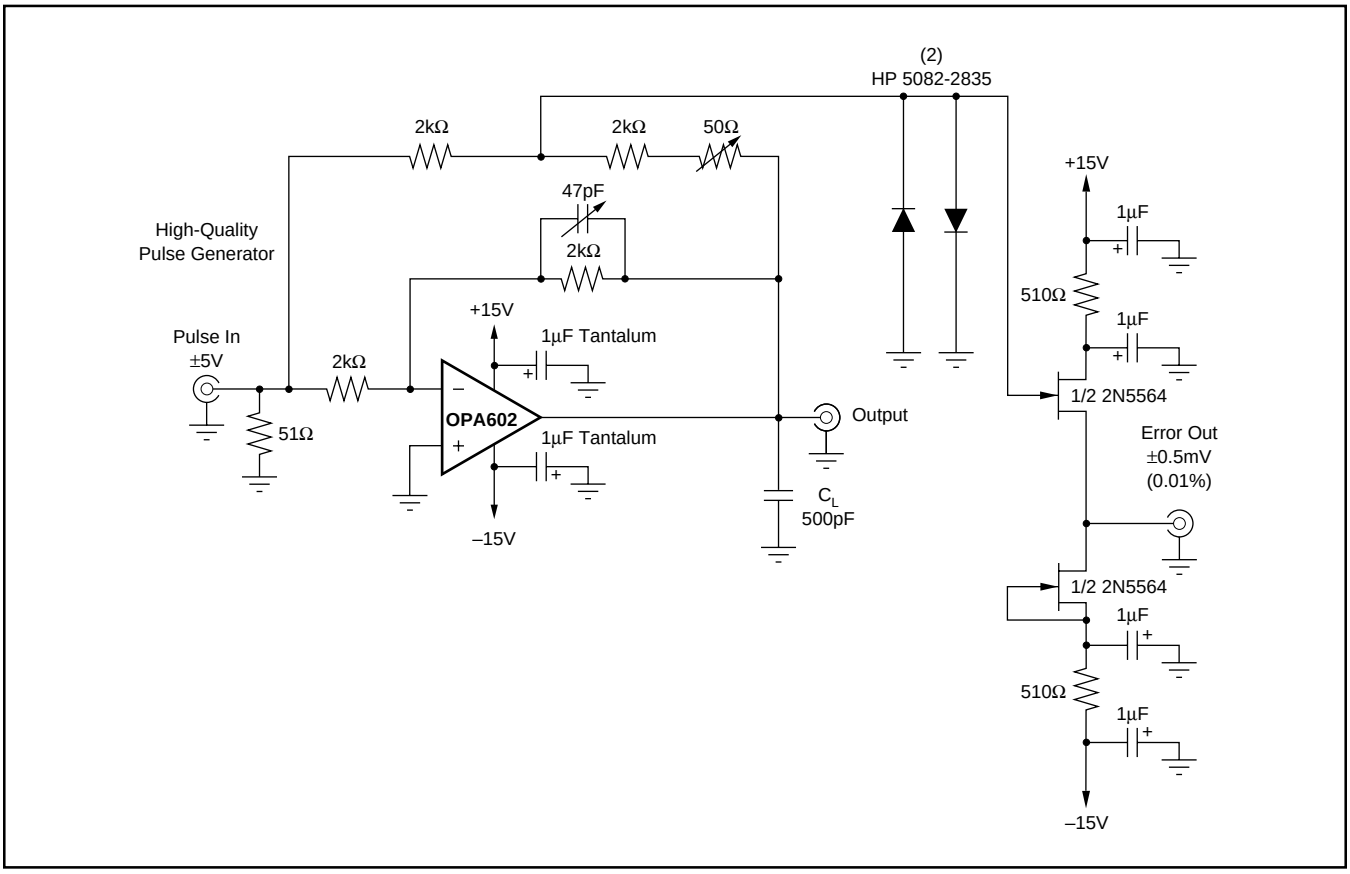
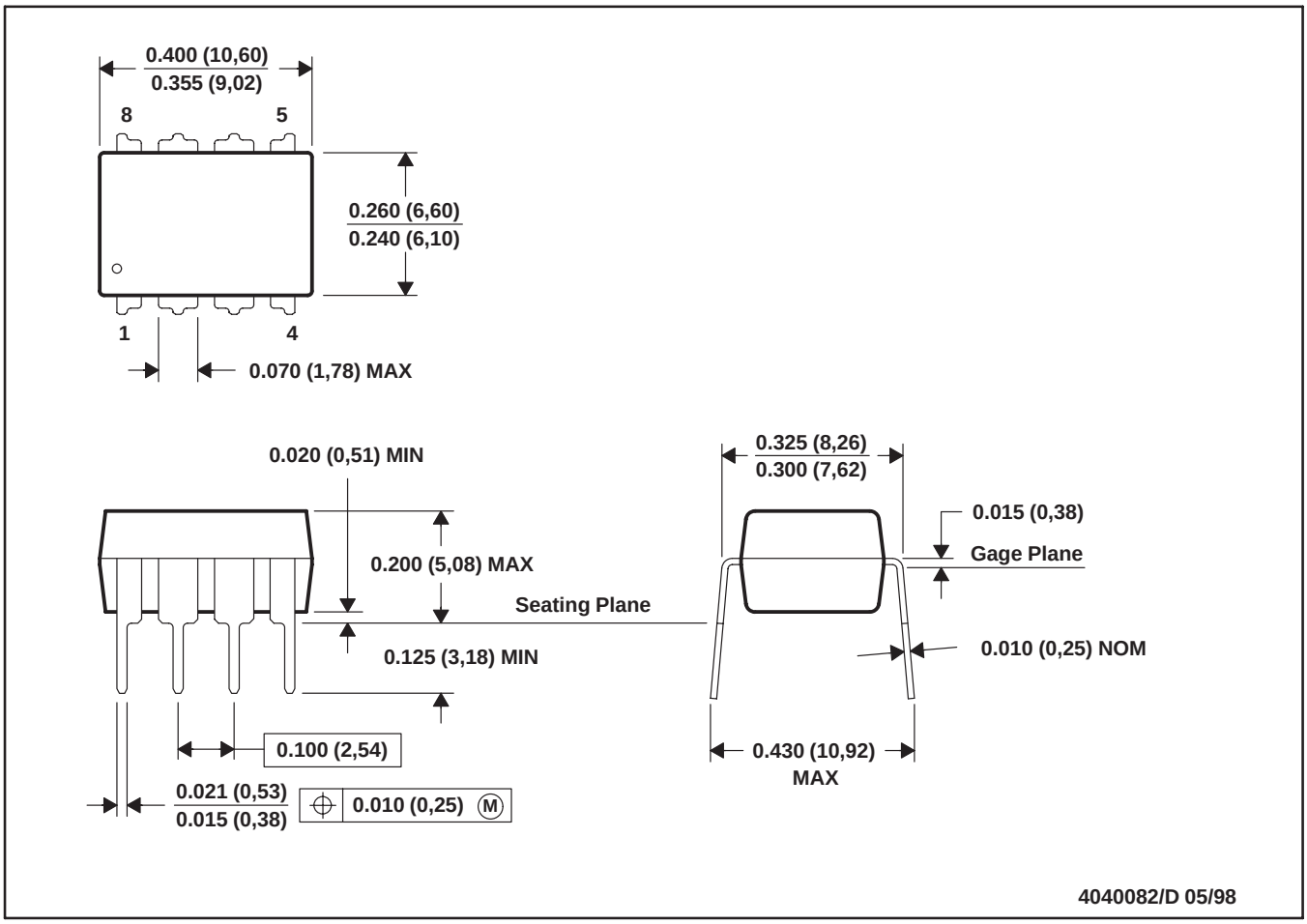


FIGURE 4. Settling Time and Slew Rate Test Circuit.

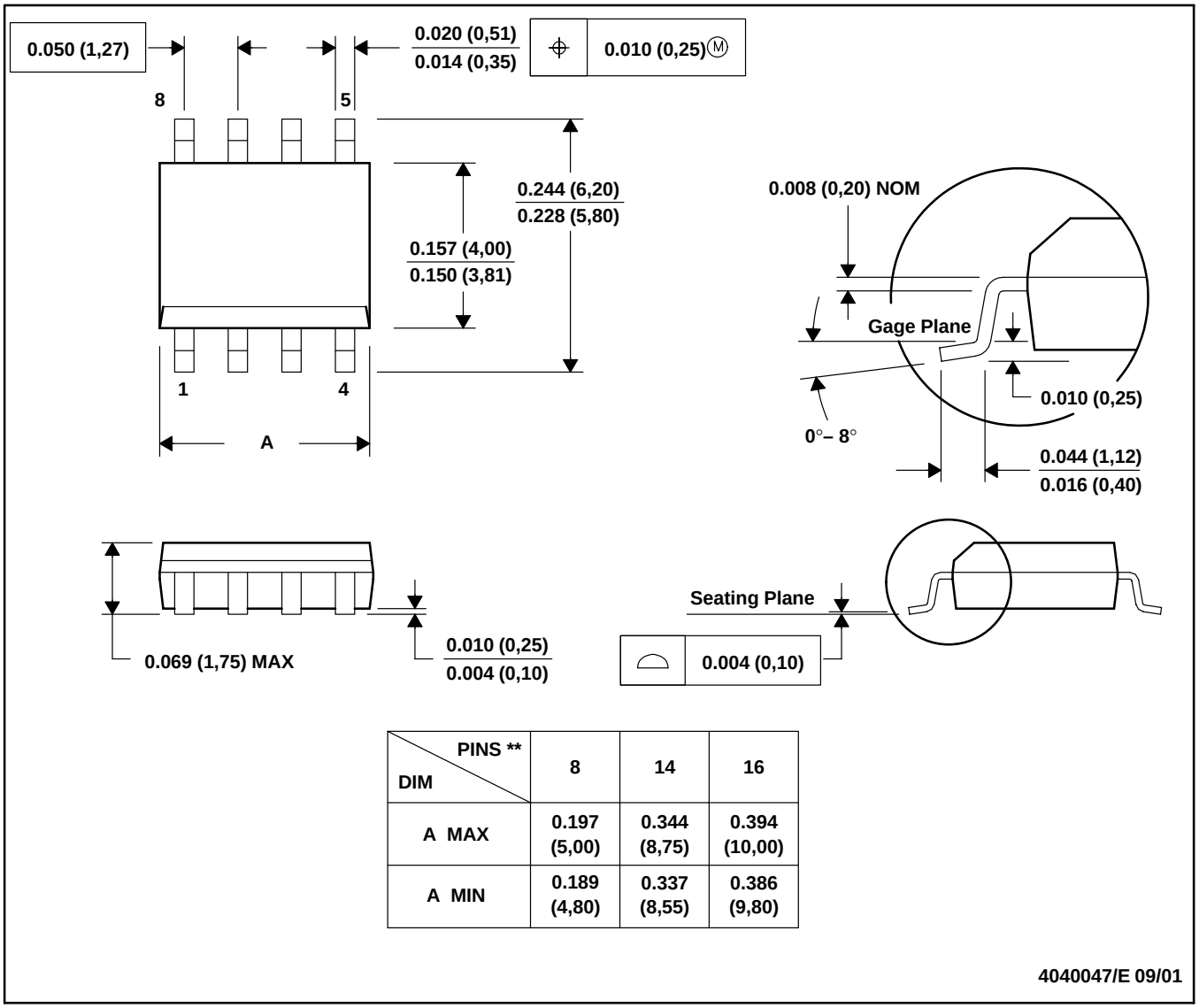
P (R-PDIP-T8) **PLASTIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

8 PINS SHOWN



DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

4040047/E 09/01

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA602AU	Last Time Buy	Production	SOIC (D) | 8	75 | TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	OPA 602AU
OPA602AU.A	NRND	Production	SOIC (D) | 8	75 | TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	OPA 602AU
OPA602AU/2K5	Last Time Buy	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	OPA 602AU
OPA602AU/2K5.A	NRND	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	OPA 602AU
OPA602AU/2K5E4	Last Time Buy	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	OPA 602AU
OPA602AUE4	NRND	Production	SOIC (D) | 8	75 | TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	OPA 602AU
OPA602BP	Obsolete	Production	PDIP (P) | 8	-	-	Call TI	Call TI	-	OPA602BP

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

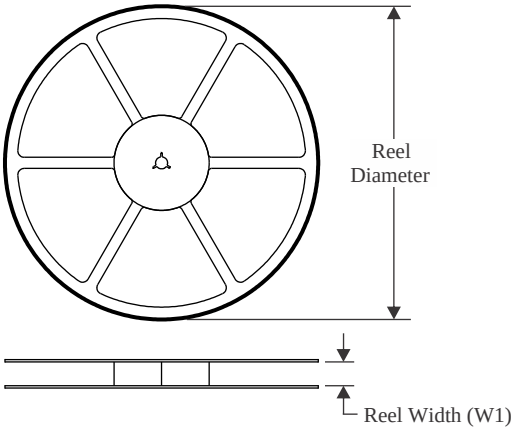
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

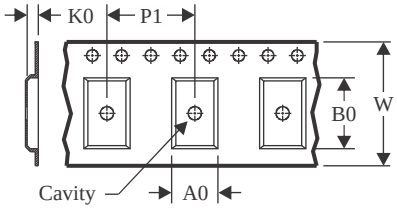
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

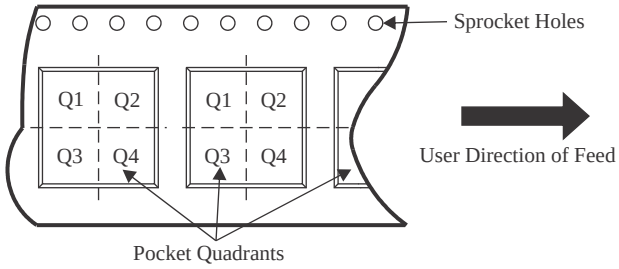


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

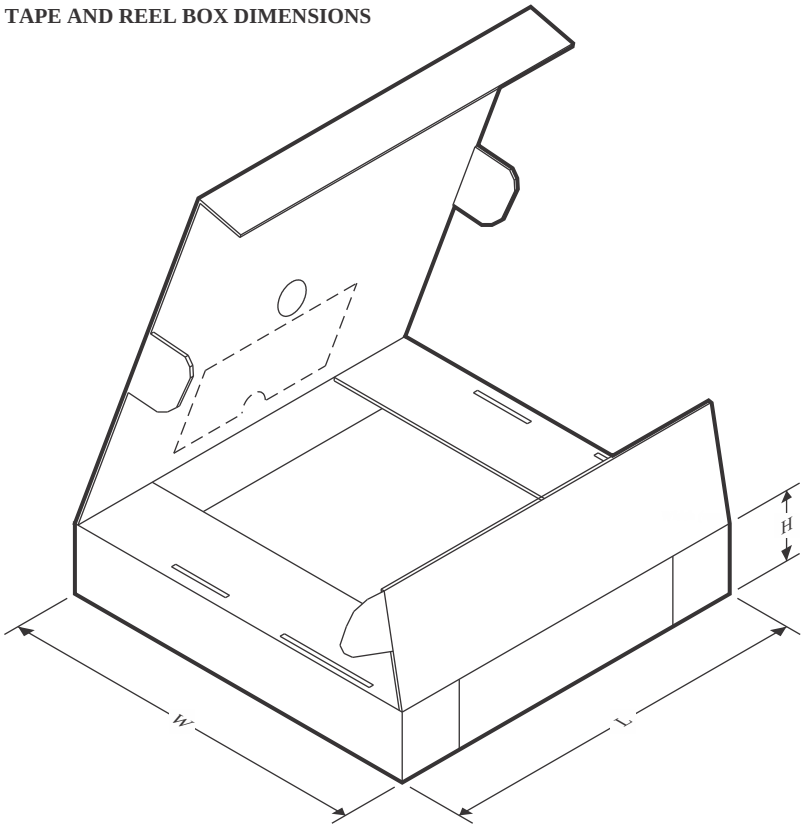
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA602AU/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

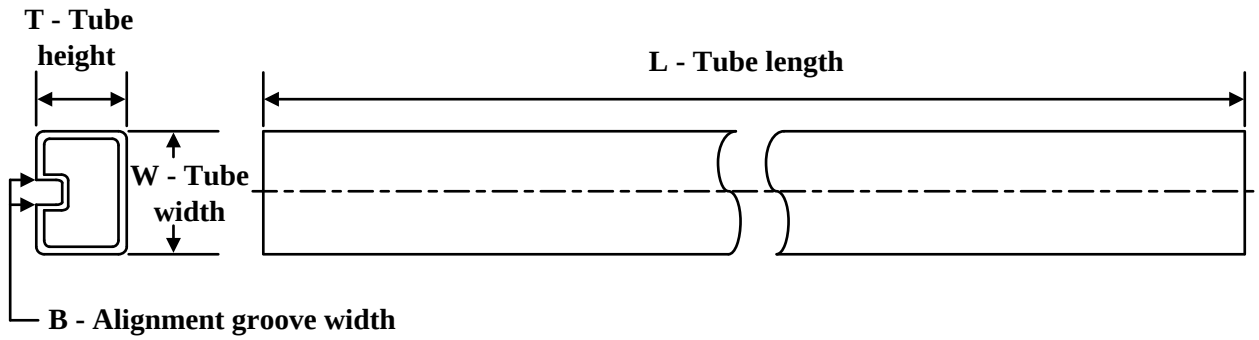
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA602AU/2K5	SOIC	D	8	2500	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
OPA602AU	D	SOIC	8	75	506.6	8	3940	4.32
OPA602AU.A	D	SOIC	8	75	506.6	8	3940	4.32
OPA602AUE4	D	SOIC	8	75	506.6	8	3940	4.32

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